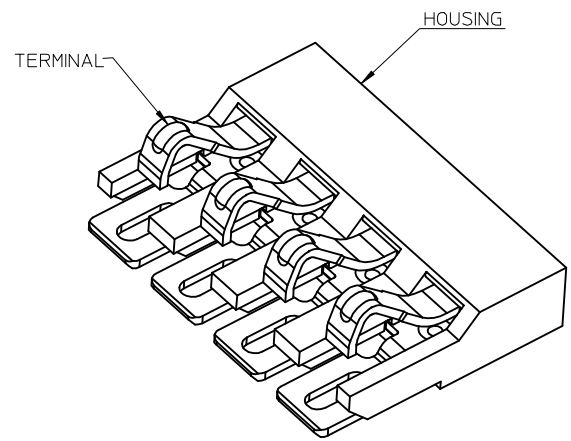
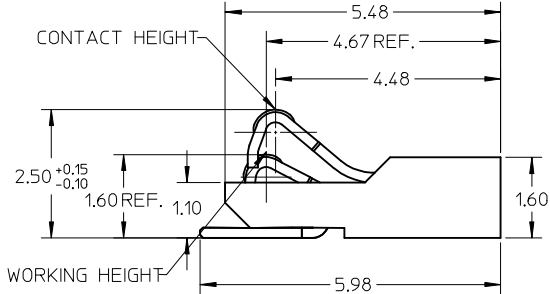
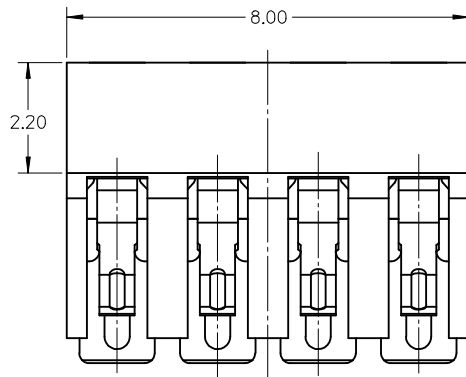
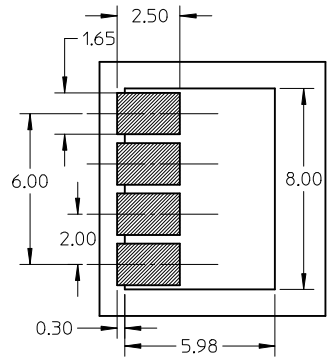
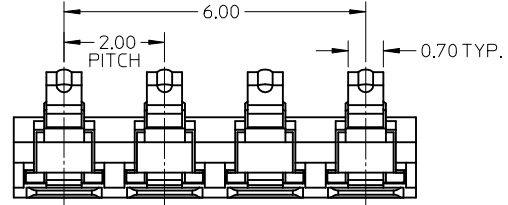


10 9 8 7 6 5 4 3 2 1

F



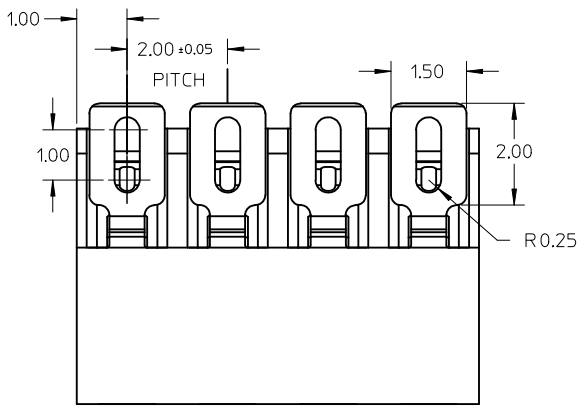
D



RECOMMENDED PCB LAYOUT
TOLERANCE: +/- 0.05

NOTE:
1.MATERIAL:
HOUSING: HIGH TEMPERATURE THERMOPLASTIC,COLOR:BLACK
TERMINAL: COPPER ALLOY
2.FINISH:
CONTACT AREA: 0.75 MICRON GOLD MIN OVER 1.25 MICRON NICKEL MIN.
SOLDER AREA: GOLD FLASH (0.075~0.125 MICRON) OVER 1.25 MICRON NICKEL MIN.
REST AREA: 1.25 MICRON NICKEL MIN.
3.COPLANARITY: 0.1 MAX AMONG THESE SOLDER TAILS.
4.PRODUCT SPECIFICATION: PS-47286-001
5.RECOMMENDED WORKING DEFLECTION RANGE:0.6-1.00 MM

C



B

A

REVISE	EC NO:	2006/09/08	QUALITY SYMBOLS	GENERAL TOLERANCES (UNLESS SPECIFIED)	DIMENSION STYLE MM ONLY	SCALE 5:1	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION
	DRW: LHS	2006/10/17	▽=0					
	CHK: XJ	2006/11/16	∇=0					
	APP: JNC							
REV	D			4 PLACES ± --- ± ---	DRAWN BY	DATE	TITLE	
				3 PLACES ± --- ± ---	SSUN	2005/07/29	2.0MM PITCH 4 CIRCUITS 0.7MM CONTACT WIDTH BATTERY CONNECTOR	
				2 PLACES ± 0.15 ± ---	CHECKED BY	DATE		
				1 PLACE ± 0.20 ± ---	XUXIANG	2006/07/06	MOLEX INCORPORATED	
				ANGULAR ± 2 °	APPROVED BY	DATE		
					JENNY CHEN	2006/07/07	MATERIAL NO.	
							472861001	
							SD-47286-001	
							SHEET NO.	
							1 OF 1	
				DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS	SIZE	THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION		
					A3			

9 8 7 6 5 4 3 2 1